

KP-1608F3C

KP-1608SF4C

### Features

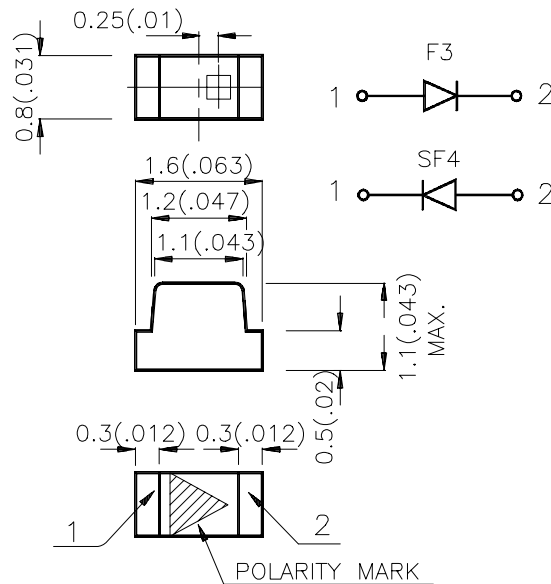
- WATER CLEAR LENS AVAILABLE.
- 1.6mmx0.8mm SMT LED, 1.1mm THICKNESS.
- HIGH POWER OUTPUT.
- PACKAGE : 2000PCS / REEL.

### Description

F3 Made with Gallium Arsenide Infrared Emitting diodes.

SF4 Made with Gallium Aluminum Arsenide Infrared Emitting diodes.

### Package Dimensions



#### Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.1$  (0.004") unless otherwise noted.
3. Lead spacing is measured where the lead emerge package.
4. Specifications are subject to change without notice.

## Selection Guide

Part No.	Dice	Lens Type	Po= (mW/sr) @20mA		Viewing Angle
			Min.	Typ.	2θ1/2
KP-1608F3C	GaAs	WATER CLEAR	0.5	1.2	120°
KP-1608SF4C	GaAlAs	WATER CLEAR	0.5	1	120°

Note:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

## Electrical / Optical Characteristics at T<sub>A</sub>=25°C

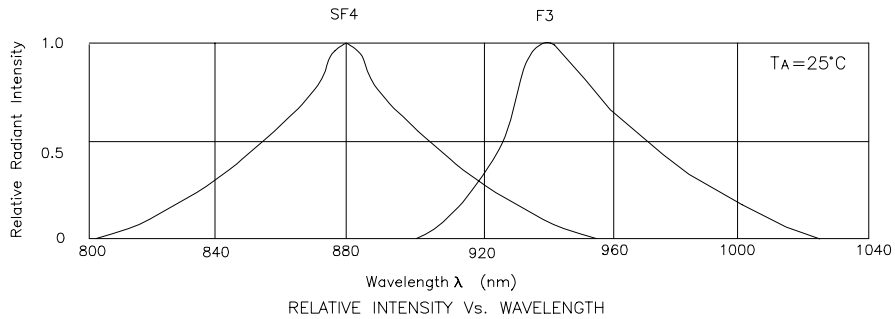
Item	P/N	Symbol	Typ.	Max.	Unit	Condition
Forward Voltage	F3 SF4	V <sub>F</sub>	1.2 1.3	1.5 1.7	V	IF=20mA
Reverse Current	F3 SF4	I <sub>R</sub>	-	10 10	μA	VR=5V
Capacitance	F3 SF4	C	90 90	-	pF	VF=0V, f=1MHz
Peak Spectral Wavelength	F3 SF4	λ <sub>P</sub>	940 880	-	nm	IF=20mA
Spectral Bandwidth	F3 SF4	Δλ <sub>1/2</sub>	50 50	-	nm	IF=20mA

## Absolute Maximum Ratings at T<sub>A</sub>=25°C

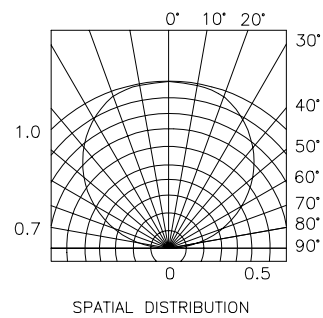
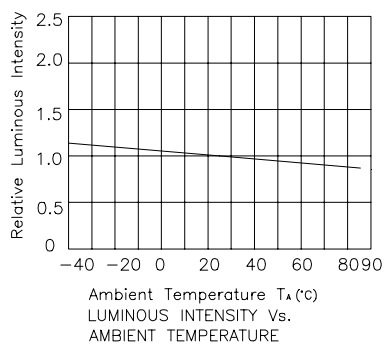
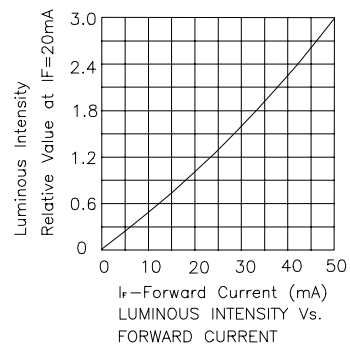
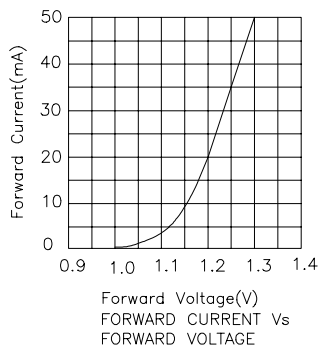
Item	Symbol	F3&SF4	Units
Power Dissipation	P <sub>T</sub>	100	mW
Forward Current	I <sub>F</sub>	50	mA
Peak Forward Current[1]	i <sub>FS</sub>	1.2	A
Reverse Voltage	V <sub>R</sub>	5	V
Operating Temperature	T <sub>A</sub>	-40~ +85	°C
Storage Temperature	T <sub>STG</sub>	-40~ +85	°C

Note:

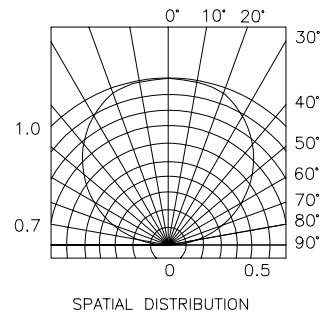
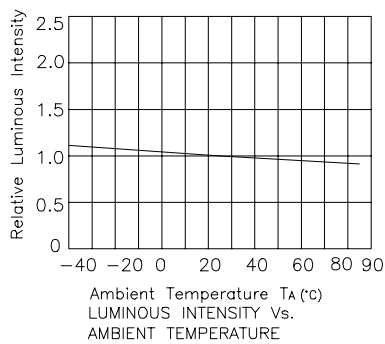
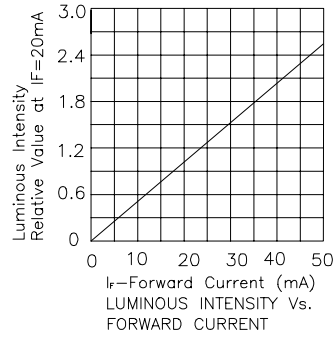
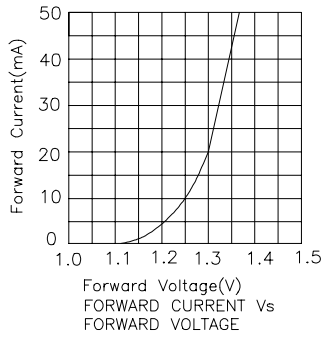
1. 1/100 Duty Cycle, 10us Pulse Width.



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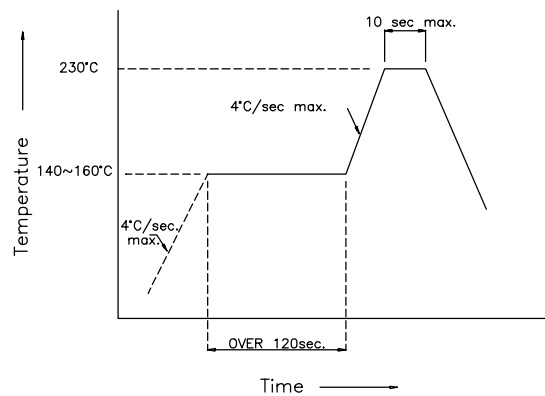


## KP-1608SF4C

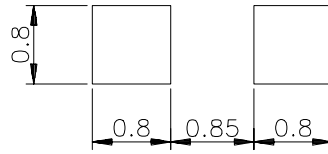


## KP-1608F3C, KP-1608SF4C SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



## Recommended Soldering Pattern (Units : mm)



## Tape Specifications (Units : mm)

